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## Product Change Notification - JAON-22LMUS028

**Date:** 02 Aug 2016  
**Product Category:** Analog (Thermal, Power Management & Safety)  
**Notification subject:** CCB 2709 Final Notice: Qualification of 84-1LMISR8 die attach material in selected Micrel products available in 8L SOIC package at STAR assembly site.  
**Notification text:** **PCN Status:**  
 Final notification

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of AB84-1LMISR8 die attach material in selected Micrel products available in 8L SOIC package at STARS assembly site.

**Pre Change:**

Using 2600AT die attach material

**Post Change:**

Using 84-1LMISR8 die attach material

**Pre and Post Change Summary:**

|                                  | Pre Change         | Post Change        |
|----------------------------------|--------------------|--------------------|
| <b>Assembly Site</b>             | STAR assembly site | STAR assembly site |
| <b>Wire material</b>             | Au wire            | Au wire            |
| <b>Die attach material</b>       | 2600AT             | 84-1LMISR8         |
| <b>Molding compound material</b> | G600               | G600               |
| <b>Lead frame material</b>       | A194               | A194               |

**Impacts to Data Sheet:**  
None

**Change Impact:**  
None

**Reason for Change:**  
To improve manufacturability and qualify 84-1LMISR8 die attach material.

**Change Implementation Status:**  
In Progress

**Estimated First Ship Date:**  
September 28, 2016 (date code: 1639)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

| Workweek                      | August 2016 |    |    |    | September 2016 |    |    |    |    |
|-------------------------------|-------------|----|----|----|----------------|----|----|----|----|
|                               | 31          | 32 | 33 | 34 | 35             | 36 | 37 | 38 | 39 |
| Qual Report Availability      | X           |    |    |    |                |    |    |    |    |
| Final PCN Issue Date          | X           |    |    |    |                |    |    |    |    |
| Estimated Implementation Date |             |    |    |    |                |    |    |    | X  |

**Method to Identify Change:**  
Traceability code

**Qualification Report:**  
Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report. If not include we can write not include or not applicable.

**Revision History:**  
**August 2, 2016:** Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN\\_JAON-22LMUS028\\_Qual\\_Report.pdf](#)
  - [PCN\\_JAON-22LMUS028\\_Affected\\_CPN.pdf](#)
  - [PCN\\_JAON-22LMUS028\\_Affected\\_CPN.xls](#)

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Affected Catalog Part Numbers (CPN)

|                    |
|--------------------|
| PCN_JAON-22LMUS028 |
| CATALOG_PART_NBR   |
| MIC37101-1.5YM     |
| MIC37101-1.5YM-TR  |
| MIC37101-1.65YM    |
| MIC37101-1.65YM-TR |
| MIC37101-1.8YM     |
| MIC37101-1.8YM-TR  |
| MIC37101-2.1YM     |
| MIC37101-2.1YM-TR  |
| MIC37101-2.5YM     |
| MIC37101-2.5YM-TR  |
| MIC37101-3.3YM     |
| MIC37101-3.3YM-TR  |
| MIC37102YM         |
| MIC37102YM-TR      |
| MIC37152YM         |
| MIC37152YM-TR      |
| MIC39101-1.8YM     |
| MIC39101-1.8YM-TR  |
| MIC39101-2.5YM     |
| MIC39101-2.5YM-TR  |
| MIC39101-3.3YM     |
| MIC39101-3.3YM-TR  |
| MIC39101-5.0YM     |
| MIC39101-5.0YM-TR  |
| MIC39102YM         |
| MIC39102YM-TR      |
| MIC4680-3.3YM      |
| MIC4680-3.3YM-TR   |
| MIC4680-5.0YM      |
| MIC4680-5.0YM-TR   |
| MIC4680YM          |
| MIC4680YM-TR       |
| MIC4681YM          |
| MIC4681YM-TR       |
| MIC4682YM          |
| MIC4682YM-TR       |
| MIC4684YM          |
| MIC4684YM-TR       |
| MIC4690YM          |
| MIC4690YM-TR       |
| SPN030027Y         |
| SPN030027Y-TR      |